



Final Product Change Notification

201603013F01

Issue Date: 16-Mar-2016

Effective Date: 29-Jun-2016

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage

Introduction of New Clip CD0S for max die Trench 7 and 9 in SOT669.

Details of this Change

CD0S is a new clip design to be introduced for use in max die SOT669. For the T7 product types in this notification, the solder material will change from PbSn to PbSnAg for standardization.

Why do we Implement this Change

Improved product quality and reliability.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 29-Jun-2016

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
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201509011F0114-Sep-2015 28-Dec-2015 Introduction of New Clips CD0S and LCD0S for max die Trench 6 in LFPAK and LFPAK2.

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 15-Apr-2016.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name powermos.pcn@nxp.com

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NXP Quality Management Team.

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